

Ersa Dip&Print Station

Form dimensional properties for stencil order

Dimensional properties for Dip-Stencils:

For correct dimensioning of a Dip-Stencil following points have to be checked:

- **Which is the length and width of the component?**

The component dimensions have to fit into the dip pocket (length x width)

- **How deep has to be dipped into the medium?**

The component has to be dipped in to the correct depth. The medium must NOT touch the component body. The pocket depth has to be defined accordingly.

- **BGA:**

The BGA balls should be dipped in minimum 30 % and maximum 50 % of their total height.

➔ In case of dipping in too deep the component might stick at the medium!

➔ The volume displacement has to be considered, especially at large BGAs with many Balls and low pitch. The medium is pushed upwards by the volume displacement.

- **QFP, PLCC and similar:**

The feet of a QFP should be dipped in as deep as possible.

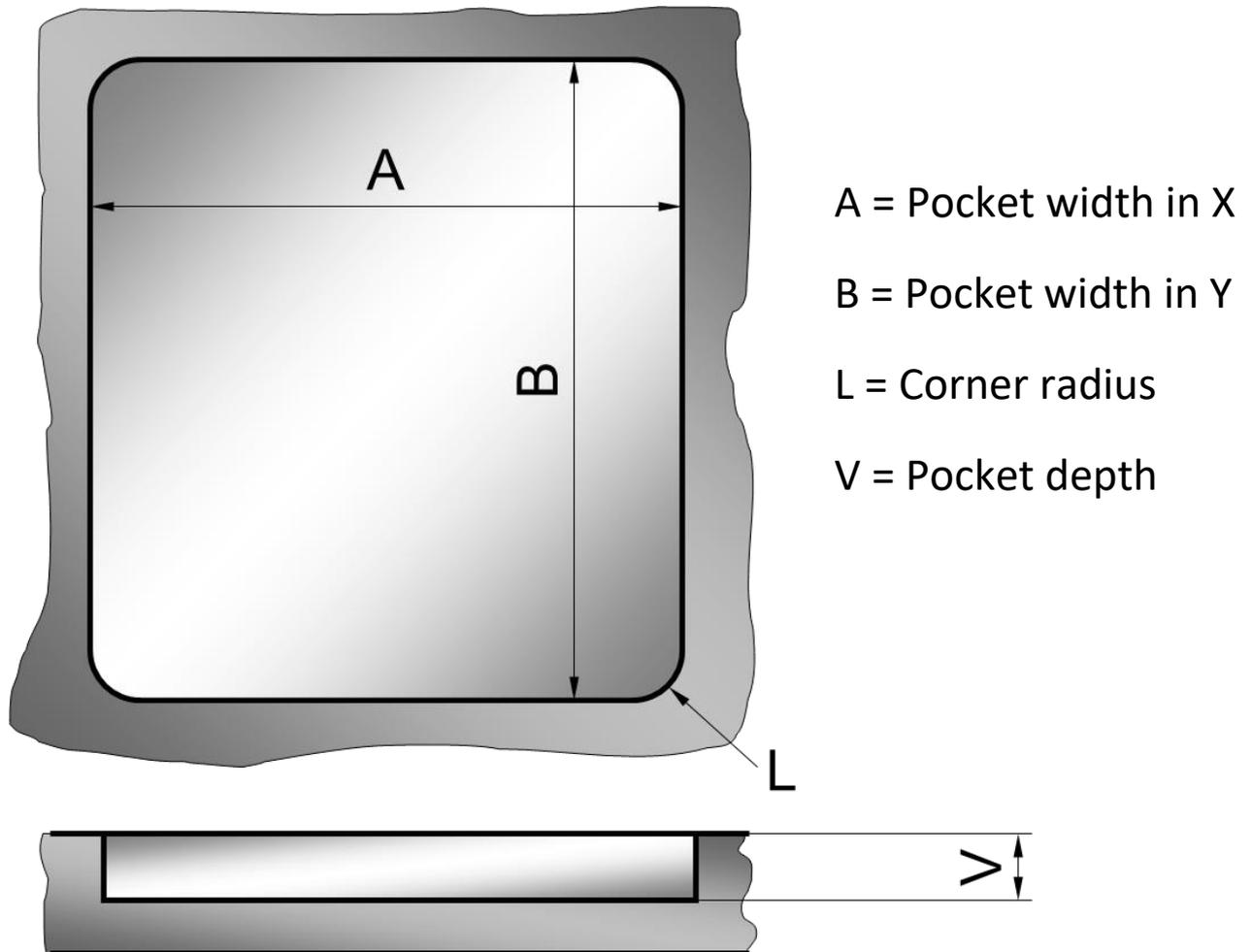
➔ Limiting factor is the clearance between the component bottom and bottom of the feet. There is a high risk for touching the component bottom by the medium caused by the mostly small clearance.

➔ The dip pocket should be just as deep as the component bottom doesn't get touched anymore.

Ersa Dip&Print Station

Form dimensional properties for stencil order

Sketch of a Dip-Stencil:



Please fill the desired measures to the table:

A		mm	Pocket width in X	Note: Normally Dip-Pockets have a square shape.
B		mm	Pocket width in Y	
L		mm	Corner radius	If not defined, standard is: 3 mm
V		µm	Pocket depth	

Tolerance of all measures, except V: - 0.00 mm + 0.25 mm

Tolerance V: - 10 µm + 10 µm